

PATENT ABSTRACTS OF JAPAN

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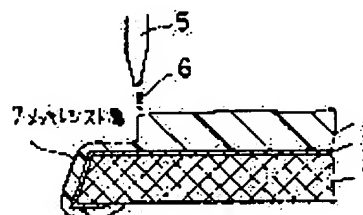
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(54) PRETREATMENT OF PLATING OF SEMICONDUCTOR WAFER

(57)Abstract:

PURPOSE: To prevent a peripheral section of a wafer from being plated and to avoid wastage of plating solution to apply good plating by spraying cleaning agent to a photoresist layer of a wafer periphery and by forming a plating resist layer to a periphery section of the wafer.

CONSTITUTION: After an under bump metal 2 and a photoresist layer 3 are formed on a semiconductor wafer 1, resist solvent 6 is sprayed from an edge rinse nozzle 5 rotating the wafer 1. A plated resist layer 7 which is thinner than the layer 3 can be thereby formed to a surface side peripheral section, a side section and a rear side peripheral section of the wafer 1. When an electrode pin is pressed to the layer 7, it can break the layer 7 easily, thereby bringing the electrode pin into contact with the metal 2. When plating is applied, the layer 7 prevents an unnecessary part from being plated, thereby avoiding wastage of plating solution and realizing good plating.



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